产品规格承认书

SPECIFICATIONS

客户:

	CUSTOMER:							
	产品名称: DESCRIPTIO 客户型号: CUSTOMER F				<u>omagneti</u>			
	产品型号:							
	OUR MODEL	NO:	<u> </u>	<u>3x</u>	(1608MA	<u>01 </u>		
	日期:			~(700 /01			
	DATE:			<u> 20</u>)21/09/01			
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TITLE: C	CHIP2450-1608	Specification			DOCUMENT NO.		1608	SPEC REV.

PBX1608MA01 Specification

Operating Temp. : -40 ℃~+85 ℃

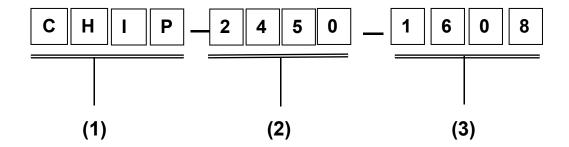
1. FEATURES:

- Light weight, compact
- Wide bandwidth, low cost
- Built-in antenna with high gain

2. APPLICATIONS:

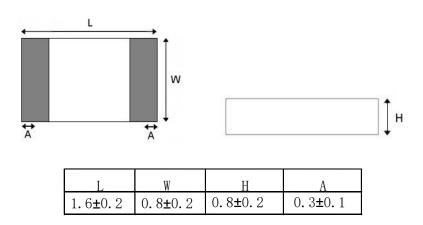
- Bluetooth, Wireless LAN, Mobile TV
- Home RF System, etc

3. PRODUCT IDENTIFICATION



- (1) Product type: Multilayer chip Antenna
- (2) Center Frequency: 2450MHz
- (3) External Dimensions (L×W) (mm): 1.6*0.8

4. SHAPE AND DIMENSIONS:

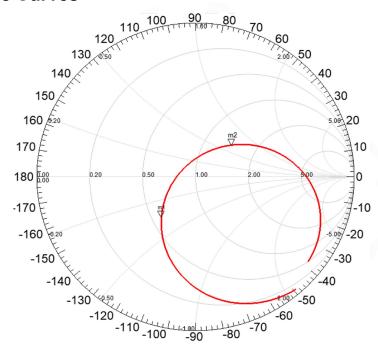


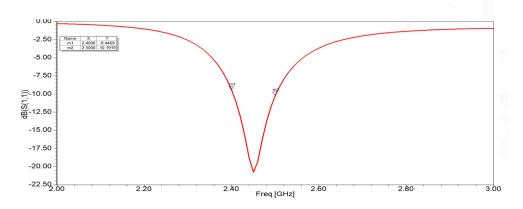
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Electrical Characteristics

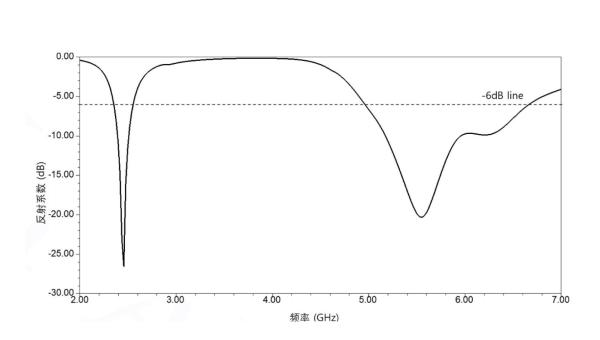
	Feature	Specification
1	Central frequency	2.45GHz&5.5GHz
2	Bandwidth	>100MHz
3	Peak gain	3dBi
4	VSWR	<2
5	Polarization	Linear
6	Azimuth beamwidth	Omnidirectional
7	Impedance	50 Ω

Characteristic Curves

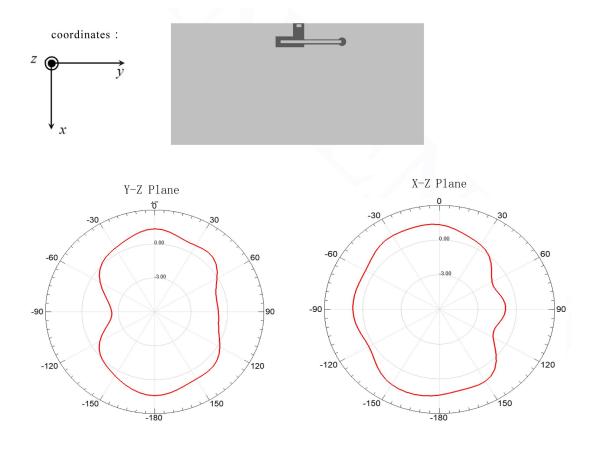




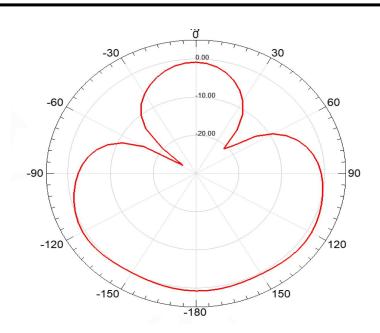
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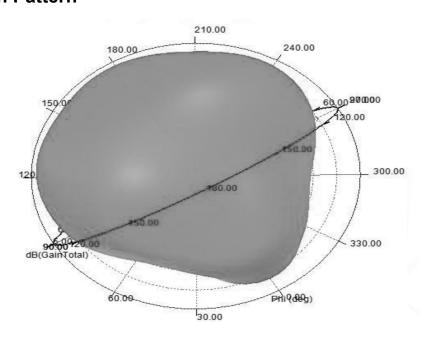
Radiation Pattern



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3D Radiation Pattern

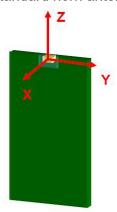


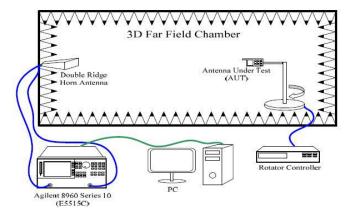
Frequency	2450MHz	5500MHz
Avg. gain	-0.85	-1.30
Peak gain	3.0	3.5
Efficiency	82%	78%

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Radiation Pattern

The Gain pattern is measured in FAR-field chamber. DUT is placed on the table of rotator,a standard horn antenna and Vector Network Analyzer is used to collect data.





Environmental Characteristics

(1) Reliability Test

Item	Condition	Specification
Thermal shock	1. 30 ± 3 minutes at -40° C $\pm5^{\circ}$ C, 2. Convert to $+105^{\circ}$ C (5 minutes) 3. 30 ± 3 minutes at $+105^{\circ}$ C $\pm5^{\circ}$ C, 4. Convert to -40° C (5 minutes) 5. Total 100 continuous cycles	No apparent damage Fulfill the electrical spec. after test.
Humidity resistance	 Humidity: 85% R.H. Temperature: 85±5° C Time: 1000 hours. 	No apparent damage Fulfill the electrical spec. after test.
High temperature resistance	1. Temperature: 150° C±5° C 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Low temperature resistance	1. Temperature: -40° C±5° C 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Soldering heat resistance	1. Solder bath temperature : $260\pm5^{\circ}\!$	No apparent damage
Solderability	The dipped surface of the terminal shall be at least 95% covered with solder after dipped in solder bath of $245\pm5^\circ\!$	No apparent damage

(2) Storage Condition

(a) At warehouse:

The temperature should be within $0 \sim 30^{\circ}\text{C}$ and humidity should be less than 60% RH. The product should be used within 1 year from the time of delivery.

(b) On board:

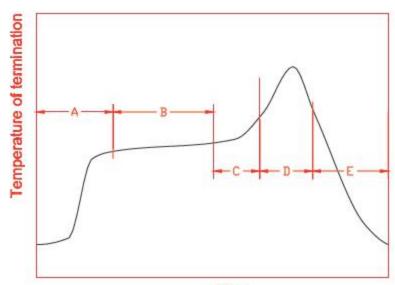
The temperature should be within -40~85°C and humidity should be less than 85% RH.

(3) Operating Temperature Range

Operating temperature range : -40° C to $+105^{\circ}$ C.

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8. Recommended Reflow Soldering



Time

Α	1 st rising temperature	The normal to Preheating temperature	30s to 60s
В	Preheating	140°C to 160°C	60s to 120s
С	2 nd rising temperature	Preheating to 200°C	20s to 40s
		if 220°C	50s∼60s
		if 230°C	40s~50s
D	Main heating	if 240°C	30s~40s
	5-7-0-2-5-0-2-5-5-5-5-5-0	if 250°C	20s~40s
		if 260°C	20s~40s
E	Regular cooling	200°C to 100°C	1°C/s ~ 4°C/s
_	2.000		

^{*}reference: J-STD-020C

(1) Soldering Gun Procedure

Note the follows, in case of using solder gun for replacement.

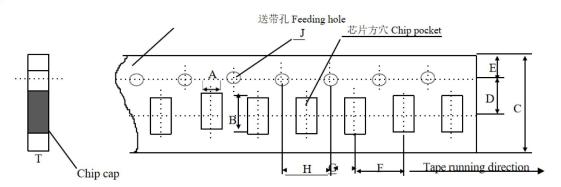
- (a) The tip temperature must be less than $350^{\circ}\,$ C for the period within 3 seconds by using soldering gun under 30 W.
- (b) The soldering gun tip shall not touch this product directly.

(2) Soldering Volume

Note that excess of soldering volume will easily get crack the body of this product.

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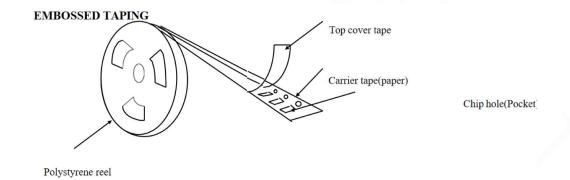
Dimensions of paper taping:



Unit: mm

代号Code 纸带规格 papersize	A	В	С	D*	E	F	G*	Н	J	T
尺寸	1.10	1.90	8.00	3.50	1.75	4.00	2.00	4.00	1.50	1.10
八寸	±0.10	±0.10	±0.10	±0.05	±0.10	±0.10	±0.10	±0.10	-0/+0.10	Max

Reel (4000 pcs/Reel)



Storage Period

The guaranteed period for solderability is 6 months (Under deliver package condition). Temperature: $5{\sim}40^{\circ}\text{C}$ /Relative Humidity: $20{\sim}70\%$

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